



# Product Change Notification

## 108626 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 108626 - 01  
**Change Title:** DQ35JO, PCN 108626-01, Product Material, SIO Supplier Change, Reason for Revision: No change to part marking  
**Date of Publication:** July 17, 2008

## Key Characteristics of the Change:

Product Material

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Jul 31, 2008
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## Description of Change to the Customer:

**Reason for Revision: No change to part marking**

Winbond SIO chip now to be manufactured by Nuvoton. The die will be the same and the vendor marking remains the same.

## Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel. This change is not expected to cause a change to the Microsoft\* Windows\* operating system.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BLKDQ35JOE 888802	888802	D82085-803	D82085-804
BOXDQ35JOE 888804	888804	D82085-803	D82085-804

## PCN Revision History:

Date of Revision:	Revision Number:	Reason:
July 9, 2008	00	Originally Published PCN
July 17, 2008	01	No change to part marking